



## Growth of TiO<sub>2</sub>/Cu films by HiPIMS for accelerated bacterial loss of viability<sup>☆</sup>



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### ABSTRACT

This study shows the first complete report on ultrathin TiO<sub>2</sub>/Cu nano-particulate films sputtered by highly ionized pulsed plasma magnetron sputtering (HiPIMS) leading to fast bacterial loss of viability. The Cu- and the TiO<sub>2</sub>/Cu sputtered films induced complete *Escherichia coli* inactivation in the dark, which was not observed in the case of TiO<sub>2</sub>. When Cu was present, the bacterial inactivation was accelerated under low intensity solar simulated light and this has implications for a potential for a practical technology. The design, preparation, testing and surface characterization of these innovative films are described in this study. The HiPIMS sputtered composite films present an appreciable savings in metals compared to films obtained by conventional sputtering methods. HiPIMS sputtering induces a strong interaction with the rugous polyester 3-D structure due to the higher fraction of the Cu-ions (M<sup>+</sup>) attained in the magnetron chamber. The Cu-leaching during the bacterial inactivation was monitored by ion-coupled plasma mass spectrometry (ICP-MS) and found to be in the ppb range. The amounts found were below the cytotoxicity level allowed by the standards related to human health. The immiscibility of Cu and TiO<sub>2</sub> in the TiO<sub>2</sub>/Cu films is shown by High Angular Dark Field (HAADF) microscopy. A mechanism for the photo-induced interfacial charge transfer (IFCT) between TiO<sub>2</sub> and Cu is suggested.

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### 1. Introduction

Antimicrobial surfaces can reduce/eliminate hospital-acquired infections (HAI) acquired on contact with bacteria surviving for long times in hospital facilities [1,2]. To preclude/decrease viral, nosocomial infections and antibiotic resistant bacteria Borkow and Gabbay [3] introduced Cu into textile fabrics. Sunada et al. [4,5], Torres et al. [6a], O. Akhavan [6b–d] and others [6e–i] have recently reported the preparation of the Cu and TiO<sub>2</sub>/Cu films by sol–gel methods with materials absorbing in the visible range. These sol–gel deposited films are not mechanically stable, in many cases their preparation is not reproducible, do not present uniformity but only low adhesion since they can be wiped off by a cloth or thumb [7]. Films obtained by direct current magnetron sputtering (DC/DCP) as reported avoid the disadvantages of Cu-films prepared by sol–gel methods [4–7] since they deposit uniform and adhesive metal film chemical bonding and mechanical interlocking leading to substrates resisting up to 120–130 °C.

In recent years physical vapor deposition (PVD) has been used to produce antimicrobial films by condensation of a vaporized precursor onto the substrate at relatively high temperatures. Page et al. [8], Foster et al. [9], Dunlop et al. [10] and Page et al. [11] have reported antibacterial film preparation of Ag and Cu films on glass and thin polymer films by PVD. TiO<sub>2</sub>, Ag, and Cu films 6 to 50 nm thick have been shown to inactivate bacteria under UV and in some cases under visible light irradiation. The disadvantages of the PVD deposition approach are the high investment costs, the high temperatures needed precluding film deposition on textiles besides the large amount of heat used requiring costly cooling systems. High power impulse magnetron sputtering (HiPIMS) has been used more recently to prepare films by applying strong electrical pulses leading to sputter layers presenting superior resistance against corrosion and oxidation [12,13]. The non-uniform deposition on rugous and complex shape substrates is one of the main problems encountered when depositing uniform Cu-films by direct current pulsed magnetron sputtering (DC/DCP) [13].

We address in this study HiPIMS sputtering on 3-D substrates leading to ultrathin uniform films showing an accelerated bacterial deactivation due to the induced high energy Cu-ions (M<sup>+</sup>) produced in the magnetron chamber, the HiPIMS plasma density and the increased effect of the applied bias voltage on the Cu-ions (M<sup>+</sup>) sputtered by HiPIMS compared to DC/DCP sputtering. We present hereby a study on Cu and TiO<sub>2</sub>/Cu films sputtered by HiPIMS describing the deposition parameters, the loss of bacterial viability under light and a detailed surface characterization. The results obtained will be compared to Cu and Cu/TiO<sub>2</sub> layers sputtered

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by DC and DCP-magnetron sputtering during the last three years [14–17]. The levels of contamination in UK hospitals have been reported to be  $\sim 10^5$  CFU/cm<sup>2</sup> in diabetic wound dressing room and in hospital residence rooms a density of  $10^2$  CFU/cm<sup>2</sup> only was found. The TiO<sub>2</sub>/Cu polyester samples described in this study present the potential to be practical candidates to avoid biofilm formation and disinfect hospital rooms not involving a high level of bacterial concentration [1–5].

## 2. Experimental section

### 2.1. Sputtering parameters, film thickness, sample composition and determination of the Cu and Ti by ICP-MS during bacterial inactivation

HIPIMS deposition of Ti and Cu was carried out in a CMS-18 Vacuum system from Kurt Lesker Ltd. evacuated to  $5.8 \times 10^{-3}$  mbar by a turbomolecular pump. The Cu- as well as the TiO<sub>2</sub> target were 50 mm in diameter, 99.99% pure from K. Lesker Ltd., UK. The TiO<sub>2</sub>/Cu target was 2 in. in diameter and had a composition of 60/40 at.% in TiO<sub>2</sub> and Cu respectively. The HIPIMS was operated at 500 Hz with pulses of 100  $\mu$ s separated by 1.9 ms, leading to a deposition rate for TiO<sub>2</sub>/Cu of 15.3 nm/min. The average power was 87.5 W (5 A  $\times$  350 V) and the power per pulse of 100  $\mu$ s was 1750 W. The 5 A current is the current at one pulse, the voltage at one pulse is 350 V and the pulses had a rectangular shape since the pulse duration was 100  $\mu$ s with an off-period of 1900  $\mu$ s.

In the case of DCP, 622 V and 0.3 A were applied during the 3 pulses of 10  $\mu$ s each within a 50 microsecond period. This gives 187 W per period or 62.3 W/pulse and an average power of 312 W/period.

The polyester used corresponds to the EMPA test cloth sample No 407. It is a polyester Dacron polyethylene terephthalate, type 54 spun, 130  $\mu$ m thick plain weave ISO 105-F04 used for color fastness determinations.

The calibration of the Cu-nanoparticulate film thickness by HIPIMS on the Si-wafers is shown in Fig. 1A. The film thickness was determined with a profilometer (Alphastep500, TENCOR). The X-ray fluorescence (XRF) determination of the Ti/Cu samples was evaluated in a PANalytical PW2400 spectrometer.

Inductively coupled plasma spectrometry (ICP-MS) was used to determine the Cu since it is a sensitive analytical technique because due to the low background and high ion transmission. The Finnigan™ ICPS used was equipped with a double focusing reverse geometry mass spectrometer able of a resolution of  $1.2 \times 10^5$  cps/ppb, and a detection limit of 0.2 ng/L. 1 cm<sup>2</sup> samples were placed in Eppendorf tubes containing 1 ml NaCl/KCl 0.08% solution. The solutions were then diluted 10 times to reach the volume necessary for the ICP-MS analyses.

### 2.2. Escherichia coli loss of viability evaluation

The samples of *Escherichia coli* (*E. coli* K12) were obtained from the Deutsche Sammlung von Mikro-organismen und Zellkulturen GmbH (DSMZ) ATCC23716, Braunschweig, Germany to test the antibacterial activity of the Cu-polyester fabrics according to a previous work reported by our laboratory [17a,b]. The bacterial counting data reported were replicated three times. To verify that no re-growth of *E. coli* occurs after the total inactivation observed in the first disinfection cycle, the samples were incubated for 24 h at 37 °C. Then bacterial suspension of 100  $\mu$ l was deposited on 3 Petri dishes to obtain replicates of the bacterial counting. These samples are incubated at 37 °C for 24 h. No bacterial re-growth was observed. Samples were irradiated in the cavity of a Suntest solar simulator with a light dose of 50 mW/cm<sup>2</sup>. The statistical analysis of the results was performed for the decrease of the bacterial CFU values reporting the standard deviation values for the runs showing the fastest bacterial inactivation. The average values were compared by one-way analysis of variance and with the value of statistical significance.

### 2.3. Diffuse reflectance spectroscopy (DRS), electron microscopy (TEM, HAADF) and XRD of samples

Diffuse reflectance spectroscopy was carried out using a Perkin Elmer Lambda 900 UV–VIS–NIR spectrometer provided for with a PELA-1000 accessory within the wavelength range of 200–800 nm and a resolution of 1.0 nm. The absorption of the samples was plotted in Kubelka–Munk (KM) arbitrary unit vs wavelength. Irradiation of the samples was carried out in a tubular cavity of a Suntest Hereaus GmbH solar simulator, Hanau, Germany.

Transmission electron microscopy was carried out in a Philips CM-12 (field emission gun, 300 kV, 0.17 nm resolution) microscope at 120 kV to measure grain size of the TiO<sub>2</sub>/Cu films. The textiles were embedded in epoxy resin 45359 Fluka and the fabrics were cross-sectioned with an ultramicrotome (Ultracut E) and at a knife angle at 35°. High-Angle Annular Dark-Field (HAADF) imaging was used to map the scanning electron microscopy (STEM). These images (Z-contrast images) are obtained by collecting the scattered electrons passing through the objective provided with an annular dark-field detector.

Crystal structures were characterized by X-ray diffraction (XRD) and recorded on an X'Pert MPD PRO from PANalytical equipped with a secondary graphite (002) monochromator and an X'Celerator detector operated in Bragg–Brentano geometry. A step size of 0.0081 was chosen and an acquisition time of 2 min per degree.

### 2.4. X-ray photoelectron spectroscopy (XPS) and detection of highly oxidative radicals in the sputtered samples

An AXIS NOVA photoelectron spectrometer (Kratos Analytical, Manchester, UK) equipped with monochromatic AlK $\alpha$  ( $h\nu = 1486.6$  eV) anode was used during the study. The electrostatic charge effects on the samples were compensated by means of the low-energy electron source working in combination with a magnetic immersion lens. The carbon C1s line with position at 284.6 eV was used as a reference to correct for charging effects. The XPS spectra for the Cu-species were analyzed by means of spectra deconvolution software (CasaXPS-Vision 2, Kratos Analytical UK). The percentage surface atomic concentration of some elements was determined by fitting of the peak areas using known sensitivity factors [18a]. Spectrum background was subtracted according to the Shirley subtraction GL(30) program attached to the Kratos unit [18b].

The detection of the oxidative species (mainly OH-radicals) in the TiO<sub>2</sub>/Cu sputtered samples was carried out according to Ishibashi et al. [19]. Terephthalic acid 99% was an ACROSS reagent. The fluorescence spectrum of the 2-hydroxyterephthalic acid generated by the reaction of terephthalic acid with OH was measured on a Perkin Elmer LS-50B fluorescence spectrometer.

## 3. Results and discussion

### 3.1. Sample film thickness bacterial loss of viability, diffuse reflectance spectroscopy (DRS) and determination of elusive Cu

Fig. 1A shows the results of the thickness calibration for HIPIMS sputtered Si-wafers at 5 A for Cu, TiO<sub>2</sub> and TiO<sub>2</sub>/Cu 60%/40% target. The fastest bacterial inactivation leading to complete inactivation was observed when the polyester sputtered for 150 s with the TiO<sub>2</sub>/Cu target (Fig. 1B) depositing a composite film 38 nm thick. This is equivalent to  $\sim 190$  layers, 0.2 nm thick with  $10^{15}$  atoms/cm<sup>2</sup> and deposited at a rate of 15.3 nm/min or  $7.6 \times 10^{16}$  atoms/cm<sup>2</sup>/min. X-ray fluorescence in Table 1 shows the content of TiO<sub>2</sub> and CuO with increased sputtering time. When using the TiO<sub>2</sub>/CuO 60%/40% target a ratio of TiO<sub>2</sub>/CuO of 4–5 times was observed for the different sputtering times.

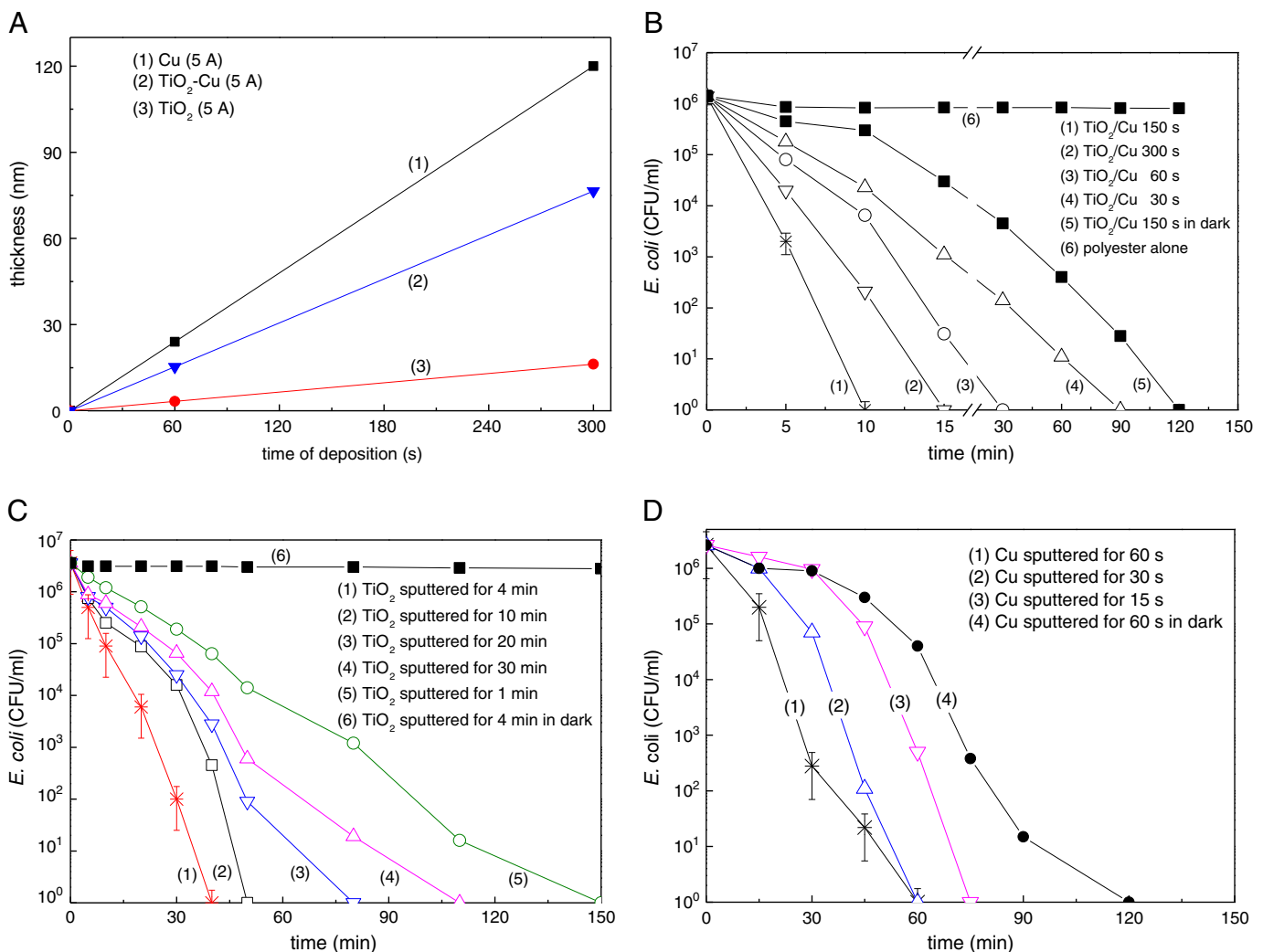
The bacterial loss of viability in Fig. 1B, trace 6 shows that no bacterial loss of viability occurs on polyester alone under light irradiation. Samples sputtered for 150 s induced a slow loss of bacterial viability

within 120 min in the dark. Under actinic light radiation, traces 3 and 4 indicate that sputtering times of 30 s and 60 s induce faster bacterial loss of viability kinetics. A sputtering time of 150 s induced the shortest inactivation time (trace 1). Sputtering for 300 s induce bacterial inactivation taking longer times compared to samples sputtered for 150 s. Therefore, the amount of  $\text{Cu}^0$  is not the main species leading to bacterial inactivation. A sputtering time of 150 s is seen to lead to the most favorable structure-reactivity for the Cu-polyester leading to the shortest *E. coli* inactivation. This sample presents the highest amount of Cu-sites held in exposed positions interacting on the surface or close to the polyester surface with *E. coli* leading to bacterial loss of viability [17a]. The surface bactericide action seems to be due to a synergic effect introduced by the  $\text{TiO}_2/\text{Cu}$  layers since longer times were observed when sputtering  $\text{TiO}_2$  as shown next in Fig. 1C.

Fig. 1C shows the bacterial inactivation kinetics by the HIPIMS  $\text{TiO}_2$  sputtered samples. As shown in Fig. 1C no bacterial inactivation takes place in the dark but the bacterial inactivation becomes faster for HIPIMS sputtering times between 1 min (trace 5) and 4 min (trace 2). Longer deposition times between 10 and 30 min did not accelerate the

loss of viability kinetics due to the fact that an increased  $\text{TiO}_2$  thickness >12 nm sputtered within 4 min leads to: a) bulk inward diffusion of the charge carriers generated on  $\text{TiO}_2$  under light leading to highly oxidative radicals [20,21], and b) longer sputtering times which facilitate the  $\text{TiO}_2$  inter-particle growth decreasing the  $\text{TiO}_2$  contact surface with bacteria [14,15]. The  $\text{TiO}_2$  bactericide inactivation mechanism has been reported and will not be discussed further in this study [6,7,20]. Fig. 1D shows the *E. coli* inactivation within 60 min for HIPIMS Cu-sputtered samples within 15, 30, and 60 s. This inactivation time is longer than the time reported in Fig. 1B suggesting a synergic effect between  $\text{TiO}_2$  and Cu leading to a faster loss of viability.

Fig. 1E presents the results for the diffuse reflectance spectroscopy (DRS) for the  $\text{TiO}_2/\text{Cu}$  samples used to evaluate the bacterial inactivation (Fig. 1B). The absorption in Kubelka–Munk units shows an agreement with the data reported for  $\text{TiO}_2$  and Cu in Table 1, showing that  $\text{TiO}_2$  is the main surface element. The  $\text{Cu}/\text{Cu}_2\text{O}/\text{CuO}$  absorption increases with longer Cu-sputtering times up to 300 s [22]. The weak absorption from 400 to 500 is due to the interfacial charge transfer (IFTC) from the  $\text{TiO}_2$  to CuO. The optical absorption between 500 and 600 nm is due to the



**Fig. 1.** A. Thickness calibration of: (1) Cu, (2)  $\text{TiO}_2$ -Cu and (3)  $\text{TiO}_2$  HIPIMS-sputtered under current intensity of 5 A. B. *E. coli* survival on  $\text{TiO}_2/\text{Cu}$  HIPIMS-sputtered on polyester for different times in the dark and under Osram Lumilux 18 W/827 actinic lamp (4 mW/cm<sup>2</sup>). C. *E. coli* survival on  $\text{TiO}_2$  HIPIMS-sputtered (5 A) on polyester for different times in the dark and under Osram Lumilux 18 W/827 actinic lamp (4 mW/cm<sup>2</sup>). D. *E. coli* survival on Cu HIPIMS-sputtered for different times in the dark and under Osram Lumilux 18 W/827 actinic lamp (4 mW/cm<sup>2</sup>). E. DRS of  $\text{TiO}_2/\text{Cu}$  polyester samples sputtered by HIPIMS for different times with 5 A (90 W). F. *E. coli* survival on  $\text{TiO}_2/\text{Cu}$  HIPIMS-sputtered samples for 150 s under different light intensities by an Osram Lumilux 18 W/827 actinic lamp. G. *E. coli* survival on  $\text{TiO}_2/\text{Cu}$  HIPIMS-sputtered sample for 150 s under an Osram Lumilux 18 W/827 actinic lamp (4 mW/cm<sup>2</sup>) up to the 8th repetitive cycle. H. Concentration of ions eluted into the solution determined by ICP-MS up to the 8th recycling of  $\text{TiO}_2/\text{Cu}$  samples inactivating *E. coli* K-12 under solar simulated light irradiation.

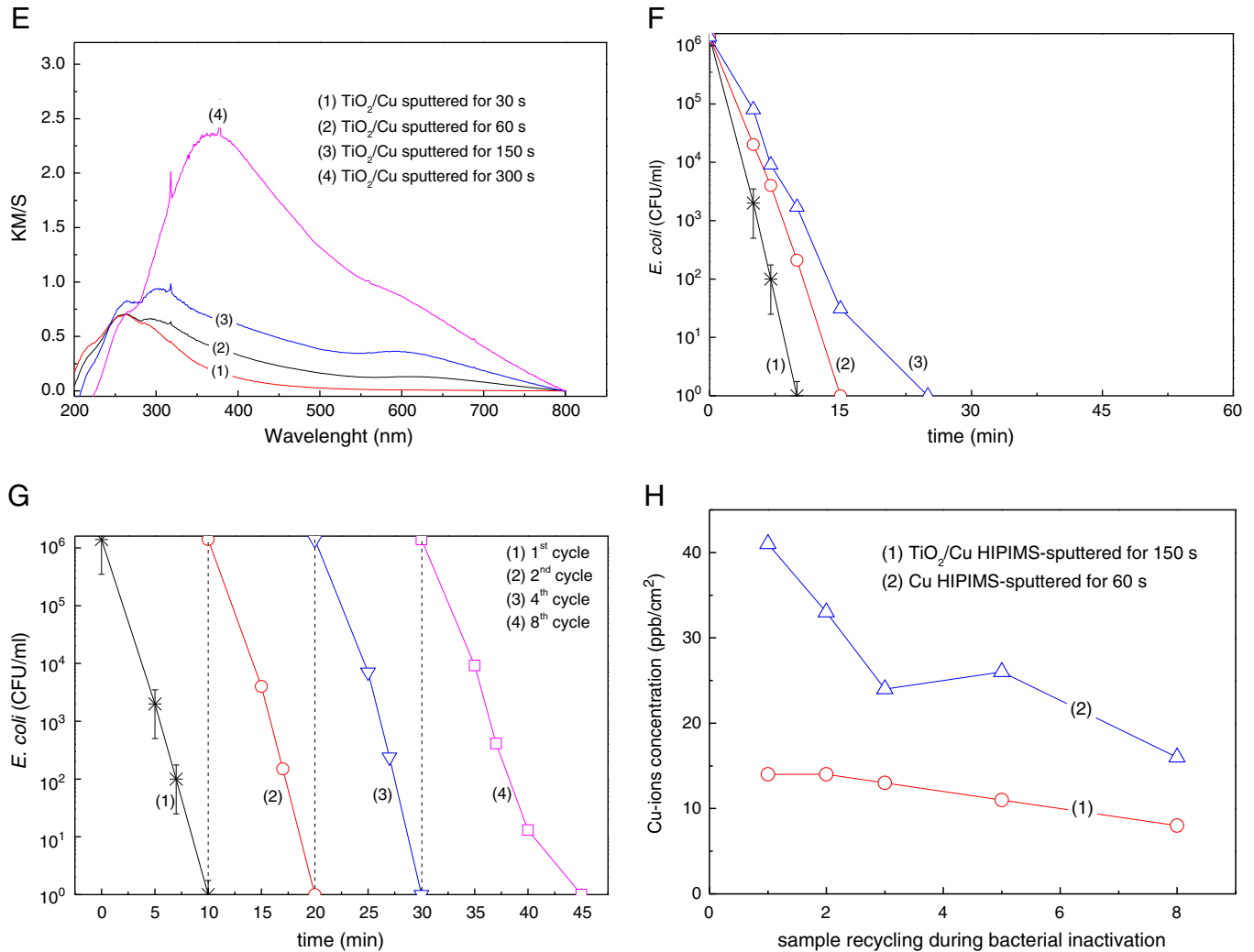


Fig. 1 (continued).

interband transition of Cu<sub>2</sub>O. The absorption between 600 and 800 nm has been attributed to the exciton band and the CU (II) d–d transition.

The rough UV–vis reflectance data cannot be used directly to assess the absorption coefficient of the sputtered polyester because of the large scattering contribution to the reflectance spectra. Normally, a weak dependence is assumed for the scattering coefficient *S* on the wavelength. The KM/S values for the samples in Fig. 1E are

**Table 1**  
TiO<sub>2</sub> and Cu loadings determined by X-ray fluorescence for the HIPIMS sputtered polyester samples used in this study.

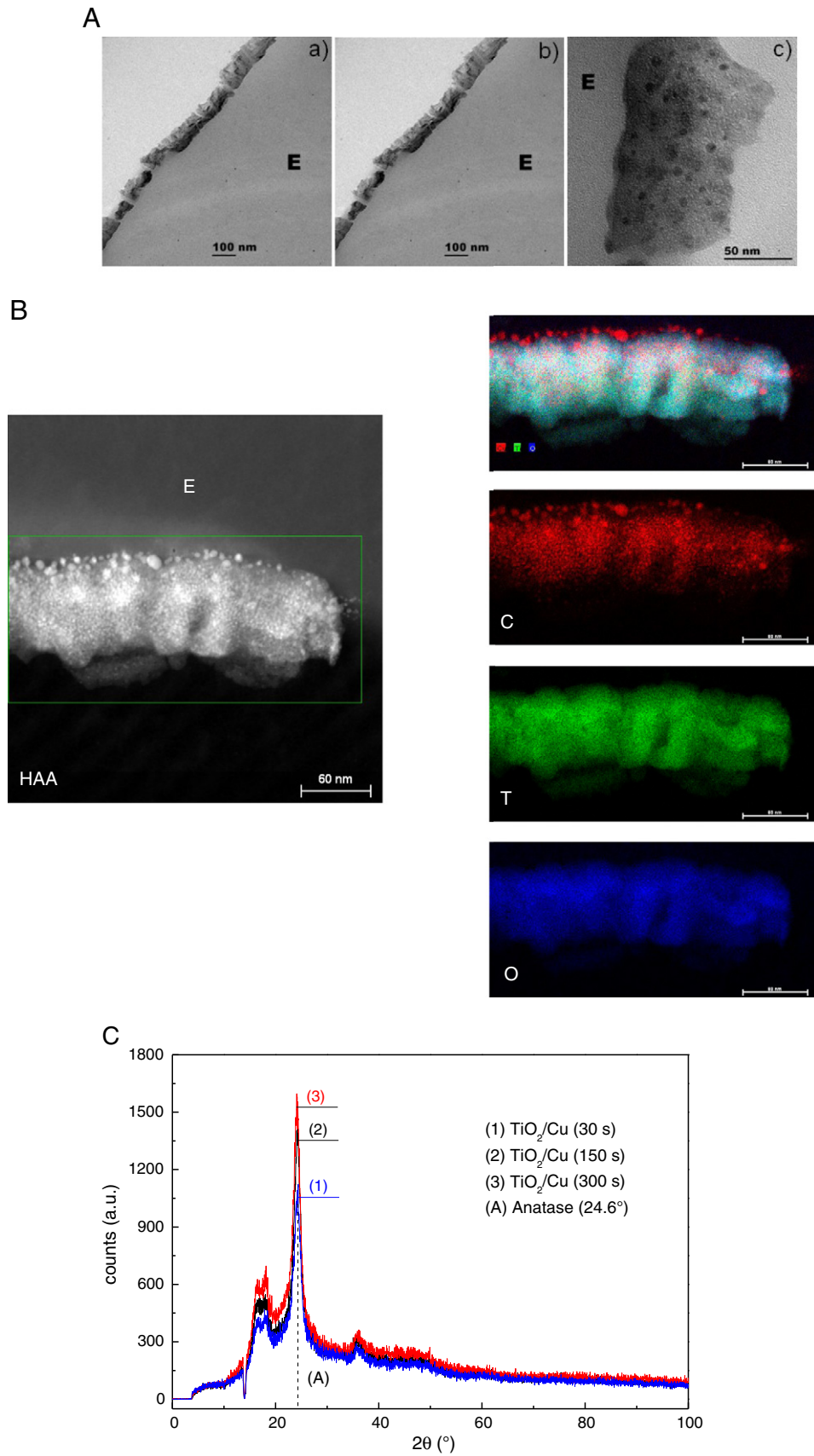
Samples	wt.% CuO/wt polyester	wt.% TiO <sub>2</sub> /wt polyester	Current intensity
TiO <sub>2</sub> (30 min)	–	0.513	5 A
TiO <sub>2</sub> (20 min)	–	0.382	
TiO <sub>2</sub> (10 min)	–	0.192	
TiO <sub>2</sub> (4 min)	–	0.042	
TiO <sub>2</sub> (1 min)	–	0.039	5 A
TiO <sub>2</sub> (30 s)	–	0.025	
Cu (60 min)	0.340	–	
Cu (30 s)	0.189	–	
Cu (15 s)	0.144	–	5 A
TiO <sub>2</sub> /Cu (300 s)	0.107	0.570	
TiO <sub>2</sub> /Cu (150 s)	0.088	0.446	
TiO <sub>2</sub> /Cu (60 s)	0.063	0.317	
TiO <sub>2</sub> /Cu (30 s)	0.060	0.243	

proportional to the TiO<sub>2</sub>/Cu absorption coefficient up to sputtering times of 150 s and these values are in agreement with the trend observed for the inactivation kinetics reported (Fig. 1B).

Fig. 1F shows the loss of bacterial viability due to the TiO<sub>2</sub>/Cu sample irradiated by three different light doses in the solar simulator. The loss of bacterial viability with time in Fig. 1F is shown to be a function of the intensity of the applied visible light. The mechanism will be discussed below in the section describing the results presented in Fig. 4.

Fig. 1G shows the recycling of the TiO<sub>2</sub>/Cu (150 s) sample up to the 8th cycle. No loss in activity was observed in the sample during the sample recycling. The sample was thoroughly washed after each recycling run leading to the reuse of the sample since complete bacterial loss of viability was attained after each cycle. The chemical state and environment of the CuO/Cu-ions seem not to change after the bacterial loss of viability showing the stable nature of the TiO<sub>2</sub>/Cu on the polyester fabric.

Fig. 1H shows the release of Cu-ions inactivating *E. coli* as a function of catalyst recycling. Fig. 1H shows the repetitive release of Cu-ions up to the 8th recycling as measured by ICP-MS. The release of Cu- from the TiO<sub>2</sub>/Cu samples shown in Fig. 1H was ~8 ppb/cm<sup>2</sup>. This value is lower compared to the Cu-release from the Cu-sputtered samples reaching up to ~18 ppb/cm<sup>2</sup> at the end of the 8th cycle. In both cases the small amounts of Cu are considered not to be cytotoxic to mammalian cells and proceed through an oligodynamic effect [6,17]. The Cu and TiO<sub>2</sub>/Cu induced bacterial inactivation is carried out in a way that it is not toxic to human health.



**Fig. 2.** A. Transmission electron microscopy (TEM) of: a) Cu sputtered for 150 s by HIPIMS on polyester, b)  $\text{TiO}_2/\text{Cu}$  sputtered for 30 s by HIPIMS on polyester and c)  $\text{TiO}_2/\text{Cu}$  sputtered for 150 s polyester. B. High-Angle Annular Dark-Field imaging (HAADF) images of  $\text{TiO}_2/\text{Cu}$  HIPIMS sputtered for 150 s showing the complete sample and the mapping of Cu, Ti and O by Z-contrast imaging in the TEM image of the sample. C. XRD patterns for  $\text{Cu}/\text{CuO}/\text{TiO}_2$  and  $\text{TiO}_2$  anatase highly crystallized films sputtered on polyester by HIPIMS at different times. Due to the Cu-loading  $<0.1\%$ , the Cu is not detected by the XRD and only the sharp anatase peak at the  $2\theta$  angle of  $24.6^\circ$  is shown in the XRD spectrogram.

**Table 2**

Percentage surface atomic concentration of TiO<sub>2</sub>/Cu (150 s) HIPIMS film as a function of bacterial inactivation time under simulated solar irradiation.

Samples	C	O	N	S	Ti	Cu
TiO <sub>2</sub> /Cu (150 s) at time zero	52.63	30.00	0.00	0.00	4.75	9.61
TiO <sub>2</sub> /Cu (150 s) contacted with bacteria at time zero	54.21	31.02	0.09	0.00	5.71	10.97
TiO <sub>2</sub> /Cu (150 s) at 5 min of bacterial inactivation	55.19	31.88	0.10	0.03	5.55	9.99
TiO <sub>2</sub> /Cu (150 s) at 10 min of bacterial inactivation	53.04	30.57	0.06	0.00	5.57	10.02
TiO <sub>2</sub> /Cu (150 s) at 15 min of bacterial inactivation	53.07	30.98	0.04	0.00	5.55	10.00

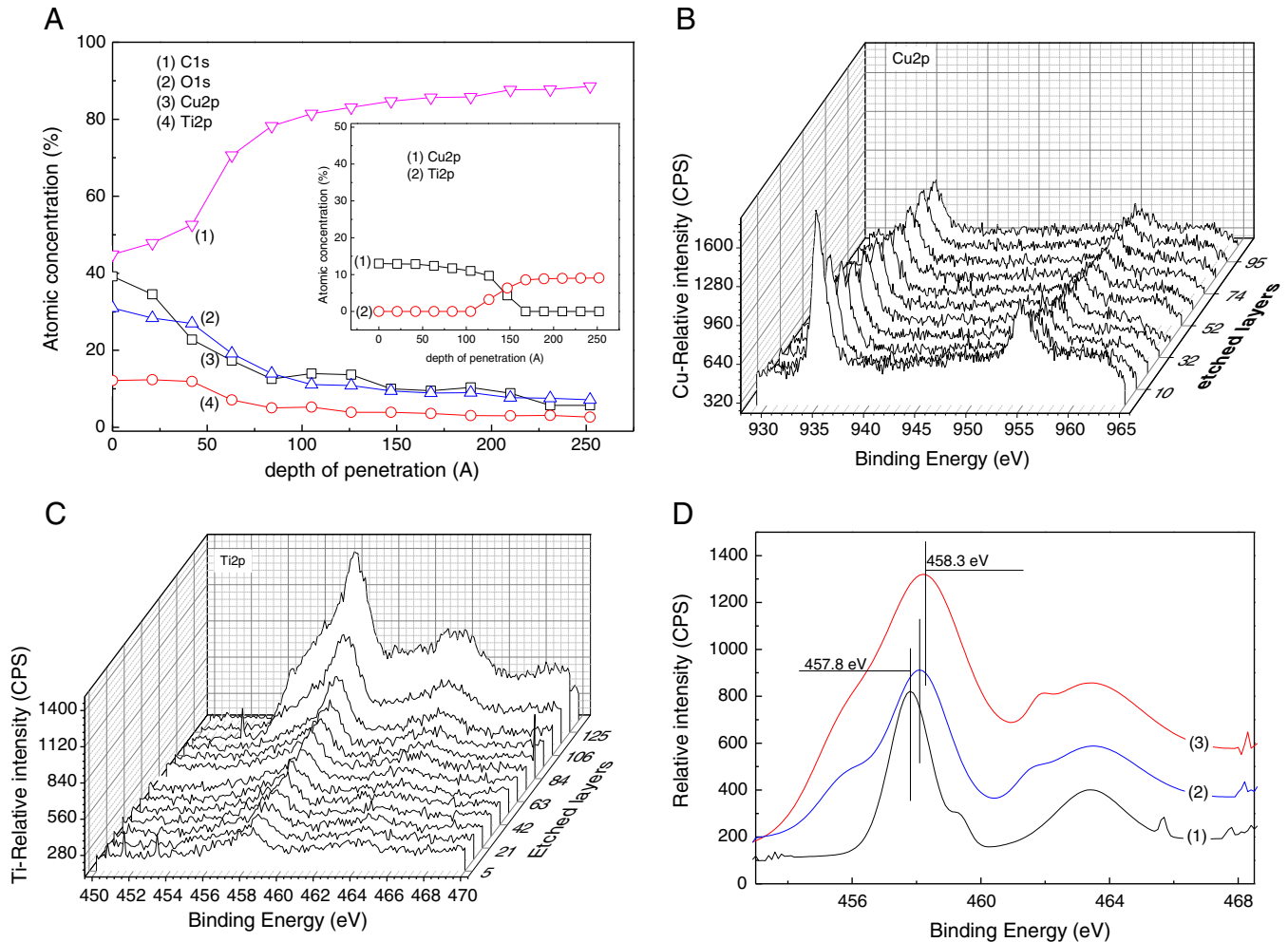
### 3.2. Steric factors and electron microscopy (TEM) and sample XRD

The particle size of the film nanoparticulate and the hydrophobic–hydrophilic balance determine to a great extent the surface photocatalytic properties. Samples sputtered for 30 s show Cu-nanoparticles between 8 and 15 nm. The TiO<sub>2</sub> samples sputtered for 150 s present sizes between 8 and 12 nm, and the TiO<sub>2</sub>/Cu samples sputtered for 150 s presented particles 5–10 nm. The TiO<sub>2</sub> binds, disperses and stabilizes the Cu-clusters on the polyester surfaces. The nanoparticles'

small size accounts partly for the favorable bacterial inactivation kinetics due to the large surface area per unit mass [14,15,20,23]. The distribution of TiO<sub>2</sub> and Cu-nanoparticles on the polyester was found to be uniform not presenting any cracks. The uniformity of the film is beneficial for the bacterial adhesion which is a primary step leading to bacterial loss of viability to proceed favorably [1,2,8]. The electronic transfer between the TiO<sub>2</sub>/Cu sample and the *E. coli* depends on the length of the charge diffusion in the composite film. This in turn is a function of the TiO<sub>2</sub> and Cu particle size and shape [20,21].

The interfacial distances between TiO<sub>2</sub> and Cu/CuO on the polyester surface range from below 5 nm and up. This allows the interfacial charge transfer (IFCT) to proceed with a high quanta efficiency [20,23]. Quantum size effects have been shown to occur in particles with sizes of 10 nm having about 10<sup>4</sup> atoms as presented by the TiO<sub>2</sub> particles with sizes of ~10 nm [23,24]. But in the CuO nanoparticles the charge recombination increases take place within shorter times due to the decrease in the available space for charge separation. Also, the decrease of the space charge layer decreases further the potential depth.

Fig. 2B presents in the left hand side TiO<sub>2</sub>/Cu microscopy contrasted by high angular annular dark field (HAADF) showing the Cu-nanoparticles to be immiscible with Ti. Cu<sup>2+</sup> does not substitute Ti<sup>4+</sup> in the TiO<sub>2</sub> lattice because of the significant difference in the radii of Ti<sup>4+</sup> (0.53 Å) and Cu<sup>2+</sup> (1.28 Å). The right hand side insets show the mapping of the Cu, Ti and



**Fig. 3.** A. XPS etching showing the microstructure of TiO<sub>2</sub>/Cu film sputtered by HIPIMS up to 240 Å (~120 atomic layers). Inset: depth profile of the TiO<sub>2</sub>/Cu film sputtered by DC/DCP. B. Depth profile of an Ar-etched TiO<sub>2</sub>/Cu HIPIMS sputtered sample showing the Cu penetration in the film. C. Depth profile of an Ar-etched TiO<sub>2</sub>/Cu HIPIMS sputtered sample showing the Ti penetration in the film. D. XPS Ti2p envelope changes at zero, 5 and 10 min during bacterial inactivation on TiO<sub>2</sub>/Cu HIPIMS samples sputtered for 150 s under solar simulated light. E. XPS Ti2p deconvolution during bacterial inactivation with TiO<sub>2</sub>/Cu HIPIMS sputtered for 150 s and irradiated by solar simulated light before and after bacterial inactivation. F. Cu2p XPS envelope at time zero, after 5 min and 15 min during bacterial inactivation on a TiO<sub>2</sub>/Cu sample sputtered for 150 s under solar simulated light. G. Cu2p peak deconvolution at time zero and 15 min after bacterial inactivation on a TiO<sub>2</sub> HIPIMS sputtered sample for 50 s under solar simulated light.

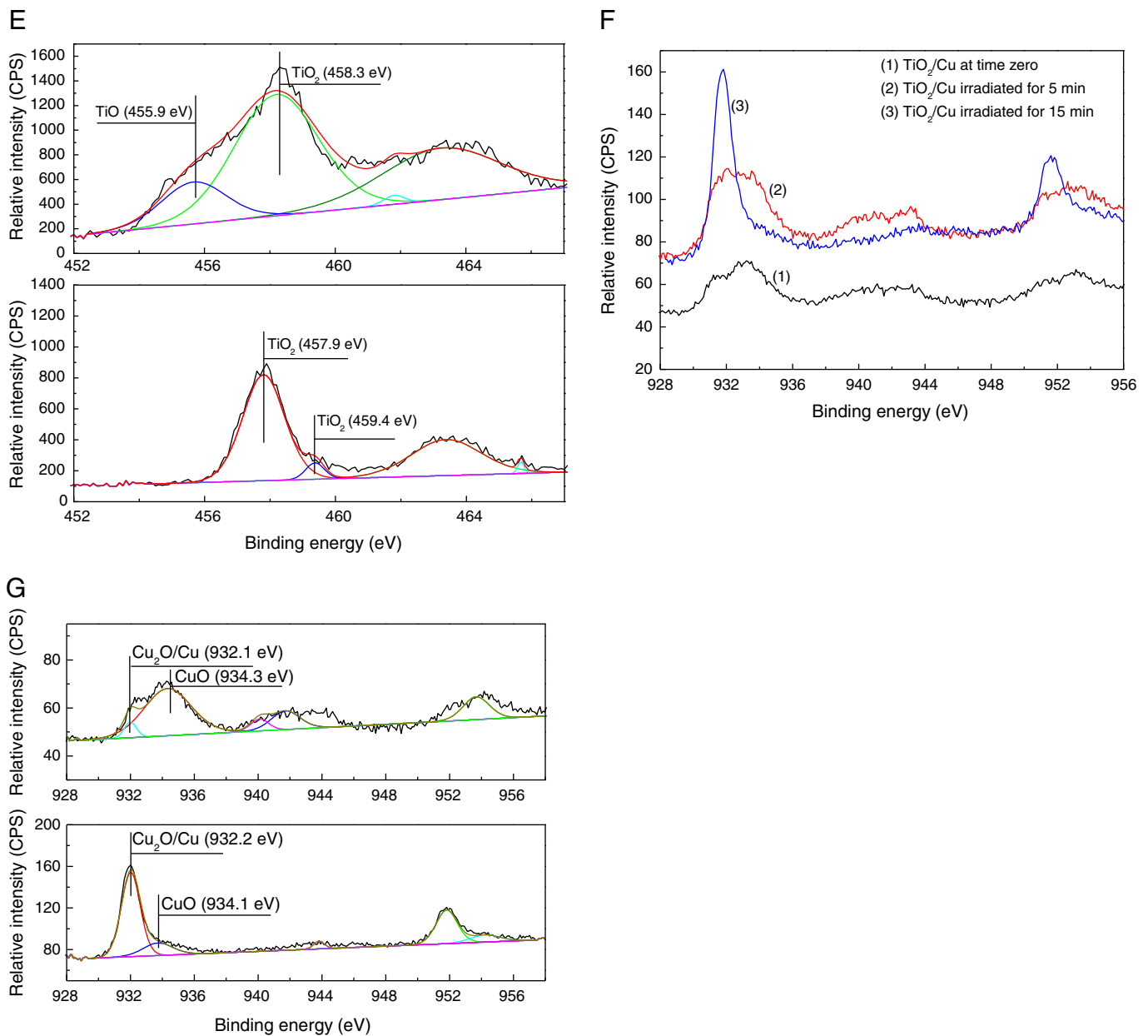


Fig. 3 (continued).

O. Due to its size, the CuO/Cu nanoparticles with particle size >8 nm are not able to penetrate into the bacteria core through the cell wall porins with diameters of 1–1.3 nm [25]. Only Cu-ions are able to diffuse through bacterial porins leading to DNA damage and finally to the total loss of bacterial viability.

Fig. 2C presents the XRD pattern for anatase and TiO<sub>2</sub>/Cu were deposited on the HIPIMS samples sputtered for 30 s, 150 s and 300 s. The distinct pattern of the Cu peaks was not observed since the loading <0.1% was too low to be detected by XRD. The Cu/Cu<sub>2</sub>O/CuO were deposited on the TiO<sub>2</sub> surface and did not lead to lattice doping. The TiO<sub>2</sub> sharp peak at 24.6° shows the highly crystallized TiO<sub>2</sub> sputtered on polyester.

### 3.3. X-ray photoelectron spectroscopy and Ar-etching of TiO<sub>2</sub>/Cu films

The surface atomic percentage composition of C, O, N, S, Ti and Cu is shown in Table 2 as a function of bacterial inactivation time for HIPIMS sputtered samples up to 15 min. Table 2 shows a constant atomic

percentage concentration implying that a rapid catalytic decomposition of the bacterial residues on the sample surface. Within 15 min the bacterial residues are destroyed enabling the catalyst recycling as shown in Fig. 1G.

Fig. 3A presents the atomic percentage concentration of Cu, Ti, O<sub>2</sub> and C of TiO<sub>2</sub>/Cu samples sputtered for 150 s as a function of depth penetration of the Ar-ions. It is readily seen that Cu, Ti and O decrease up to 240 Å due to the Ar-bombardment. The etching depth induced by the Ar-ions was referenced by the known etching value for Ta of 15 atomic layers per minute equivalent to ~30 Å/min. The penetration of the Cu

Table 3

Surface atomic concentration percentage of CuO and Cu<sub>2</sub>O on TiO<sub>2</sub>/Cu HIPIMS sputtered for 150 irradiated by solar simulated light.

	% CuO	% Cu <sub>2</sub> O
TiO <sub>2</sub> /Cu at time zero	72	27
TiO <sub>2</sub> /Cu at time of 15 min	18	80

inside the sample protects the Cu-clusters inside the 130  $\mu\text{m}$  thick polyester network during the *E. coli* inactivation process. The increase in the C-content in Fig. 3A is due to the etching removing the  $\text{TiO}_2/\text{Cu}$  layers which make available the C-content of the polyester. The inset in Fig. 3A shows the significantly lower percentage of Cu and Ti for  $\text{TiO}_2/\text{Cu}$  sputtered by DC/DCP [17]. The concentration of Ti followed a different pattern compared to the one observed when sputtering by HIPIMS and increases beyond 100  $\text{\AA}$  because Ti deposition was hindered by the Cu-layers. Fig. 3B presents the 3-D view of the Cu 2p3/2 doublet and the Cu shake-up satellites at 933.4 eV and at 933.1 eV [18a] for the  $\text{TiO}_2/\text{Cu}$  150 s HIPIMS sample. The Cu-enrichment within the 10 first layers is seen to decrease with sample depth and remain stable up to  $\sim 100$  layers. Fig. 3C shows the Ti 2p3/2 doublet peaks with a binding energies (BE) at 458.5 and 464.1 eV, increasing steadily as we go deeper into the  $\text{TiO}_2/\text{Cu}$  film up to  $\sim 125$  layers.

Fig. 3D presents the XPS envelope for the Ti2p signals at zero, 5 min and 10 min shown in the traces (1) through (3). It is readily seen that redox  $\text{Ti}^{3+}/\text{Ti}^{4+}$  processes take place during bacterial inactivation shifting the peak from 457.8 to 458.3 eV. This is  $>0.2$  eV accepted as a true change in the oxidation state of a specific species [15,18a]. Fig. 3E presents the deconvolution of the peaks for the Ti2p doublet before and after the bacterial inactivation process. Evidence is presented for the reduction from Ti(IV) to Ti(III) in Fig. 3 by the shift of the deconvoluted peak from 457.9 eV at time zero to 458.3 eV after 10 min, the end of the bacterial inactivation.

Evidence is presented in Fig. 3F–G by XPS for Cu-redox chemistry during the bacterial inactivation in addition to the redox chemistry described above in Fig. 3D and e for  $\text{Ti}^{3+}/\text{Ti}^{4+}$  states. Fig. 3F at time zero presents the experimental envelope for the XPS peaks at time zero at 934.3 eV for CuO and at 932.1 eV for  $\text{Cu}_2\text{O}$ . The  $\text{Cu}_2\text{O}$  peak in  $\text{TiO}_2/\text{Cu}$  in Fig. 3F grows during the bacterial inactivation after 5 min and after 15 min when the bacterial inactivation is complete. In agreement with Table 3 a significant growth of the  $\text{Cu}_2\text{O}$  peak is detected in Fig. 3G due to two reasons: a) the CuO initial decreases from 72% to 18% while concomitantly the  $\text{Cu}_2\text{O}$  grows from 27% to 80% in line with the redox catalysis taking place in  $\text{TiO}_2/\text{Cu}$  shifting the CuO peak in Fig. 3G to CuO 934.1 eV and b) the bacteria covering initially the  $\text{TiO}_2/\text{Cu}$  catalyst have been removed during the inactivation process. It can be suggested that the interactions between  $\text{Cu}^+/\text{Cu}^{2+}$  and  $\text{Ti}^{3+}/\text{Ti}^{4+}$  in the  $\text{TiO}_2/\text{Cu}$  samples plays an active role accelerating the bacterial inactivation. The  $\text{Ti}^{3+}/\text{Ti}^{4+}$  surface electron trappers enhance the  $\text{O}_2$  chemisorption at the surface more markedly in the  $\text{TiO}_2/\text{Cu}$  samples. This leads to a fast bacterial inactivation by  $\text{TiO}_2/\text{Cu}$  compared to Cu in Fig. 1D. The hole transition from  $\text{TiO}_2\text{vb}$  to the Cu mid band-gap states is in a second stage followed by indirect electronic transitions from the mid-gap states reaching the  $\text{TiO}_2\text{cb}$ .

#### 3.4. Mechanism of the bacteria inactivation under visible light

Fig. 4A shows the interfacial charge transfer between  $\text{TiO}_2$  and Cu in the  $\text{TiO}_2/\text{Cu}$  photocatalyst  $\text{TiO}_2/\text{Cu}$  under simulated solar irradiation. In the  $\text{TiO}_2$  semiconductor the solar irradiation induces both the  $e^-$  transfer and  $h^+$  transfer from  $\text{TiO}_2$  to CuO since the potential energy levels of the  $\text{TiO}_2\text{cb}$  and  $\text{TiO}_2\text{vb}$  lie above the  $\text{CuOcb}$  and  $\text{CuOvb}$  levels. The partial recombination of  $e^-/h^+$  in the  $\text{TiO}_2$  is hindered by the transfer of charges to the CuO facilitating the reactions occurring at the  $\text{TiO}_2\text{cb}$  and  $\text{CuOcb}$  as shown in Fig. 4A. Under simulated solar light as shown in Fig. 4A, the CuO can be reduced to  $\text{Cu}_2\text{O}$  and the  $\text{Cu}_2\text{O}$  can reduce  $\text{O}_2$  via a multi-electron process and re-oxidize to CuO. The charges generated by light in the  $\text{TiO}_2/\text{Cu}$  lead to the rapid loss of *E. coli* viability within 10 min (Fig. 1B), along  $\text{O}_2$  and CuO reduction at the  $\text{CuOcb}$  as suggested in Fig. 4A.

The interfacial charge transfer (IFCT) in the  $\text{TiO}_2/\text{Cu}$  sample seems to proceed with a high quantum efficiency since the bacterial inactivation proceeds within short times of about 10 min (Fig. 1B). But the

magnitude of the increase in the IFCT absorption of the  $\text{TiO}_2/\text{Cu}$  shown by the DRS spectra in Fig. 1E is relatively small.

The conduction band of CuO at  $-0.30$  V vs SCE (pH 7) is at a more negative potential than the potential required for the one electron oxygen reduction  $\text{O}_2 + \text{H}^+ + e^- \rightarrow \text{HO}_2^\cdot - 0.22$  V [25,26]. Furthermore, the  $\text{Cu}^{2+}$  can react with  $e^-$  (or  $\text{O}_2^-$ )  $\rightarrow \text{Cu}^+ +$  (or  $\text{O}_2$ ). The  $\text{Cu}^+$  can reduce  $\text{O}_2$  consuming electrons or be oxidized to Cu-ions by the photo-generated  $\text{TiO}_2$  holes to  $\text{Cu}^{2+}$  [27]. The  $\text{TiO}_2\text{vb}$  holes react with the surface  $-\text{OH}$  of the  $\text{TiO}_2$  releasing OH-radicals to inactivate bacteria [28].

Fig. 4B presents the increase in fluorescence of the  $\text{TiO}_2/\text{Cu}$  HIPIMS sputtered samples irradiating up to 15 min in the solar simulator. The OH-radicals originate from the reaction between the OH-radical and terephthalic acid leading to the formation of a fluorescent hydroxy-product [19]. The  $\text{TiO}_2\text{vb}$  holes in Fig. 4A have the potential to degrade polyester during the bacterial inactivation cycles. But the stable repetitive *E. coli* loss of viability reported in Fig. 1G shows that bacterial inactivation did not lead to the degradation of polyester up to the 8th recycling.

#### 3.5. DCP and HIPIMS sputtering of samples, applied power, charge density and bias voltage considerations

Fig. 5A presents the loss of viability time vs thickness for DCP and HIPIMS  $\text{TiO}_2/\text{Cu}$  sputtered films. Fig. 5A shows the much thinner  $\text{TiO}_2/\text{Cu}$  layer thickness necessary for complete bacterial inactivation sputtered by HIPIMS compared to DC/DCP. Fig. 5A shows that the HIPIMS film with a thickness of 38 nm inactivated bacteria within  $\sim 10$  min compared to a sputtered DC/DCP film 600 nm thick inducing bacterial inactivation within the same period of time.

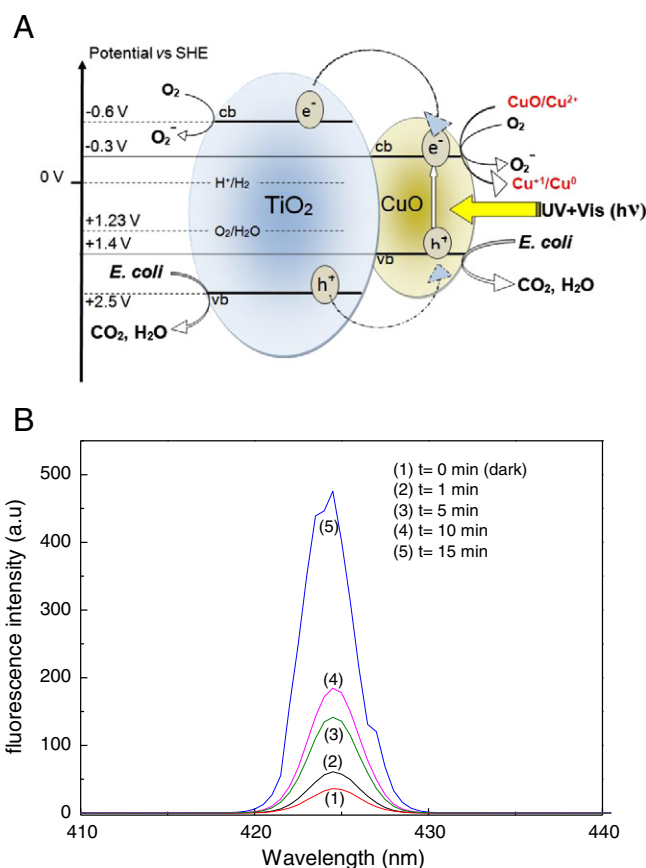
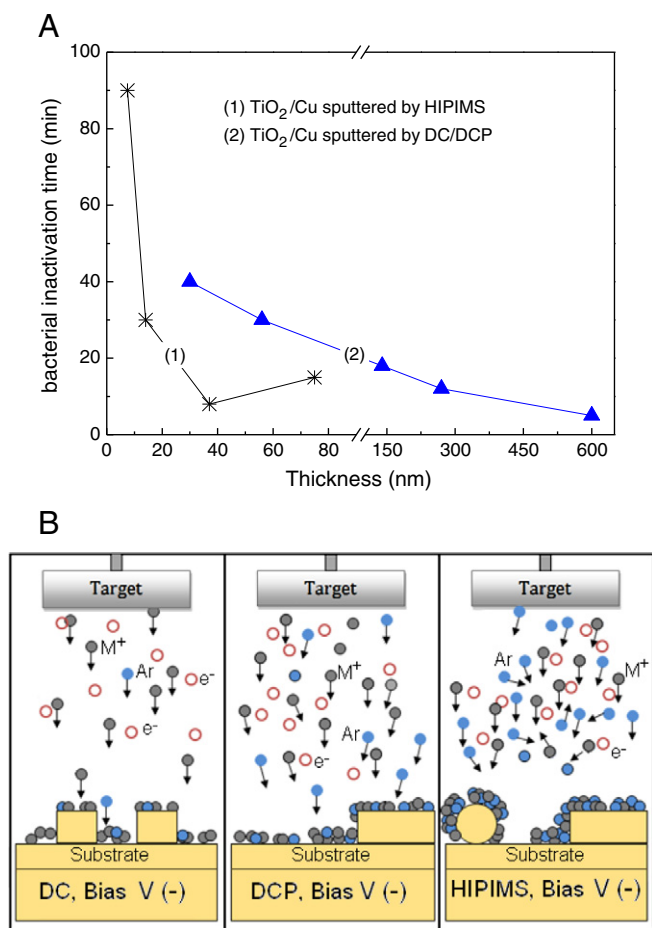


Fig. 4. Scheme of bacteria inactivation under visible light for  $\text{TiO}_2/\text{Cu}$  films on polyester. B. Fluorescence intensity as a function of irradiation time for HIPIMS sputtered 150 s samples on polyester irradiated by an Osram Lumilux 18 W/827 lamp.





**Fig. 5.** A. Bacterial inactivation time vs nominal thicknesses for HIPIMS sputtered  $\text{TiO}_2/\text{Cu}$  films and by DC/DCP sputtered layers under Osram Lumilux 18 W/827 actinic lamp ( $4 \text{ mW}/\text{cm}^2$ ) irradiation. B. Schematics of the a) DC, b) DCP and c) HIPIMS sputtering of metal-ions ( $\text{M}^+$ ) on polyester 3-D surfaces. For other details see text.

In Fig. 5B, the left hand side presents a scheme for the DC sputtering proceeding with an ionization of the Cu-ions of 1% [29]. The DCP sputtering is schematically presented in Fig. 5B (middle section) and proceeds with ionization of Cu-ions well above the values attained by DC [30]. In Fig. 5B, the right hand side involves HIPIMS sputtering leading to a Cu-ionization of ca. 70% and an electronic density of  $\sim 10^{18-19} \text{ e}^-/\text{m}^3$  [31]. The HIPIMS power per pulse was  $1750 \text{ W}/100 \mu\text{s}$ . This value is significantly higher than the power per pulse applied by DCP of  $62.3 \text{ W}/10 \mu\text{s}$ . The HIPIMS higher energy increased the ionization percentage  $\text{Cu}^0 \rightarrow \text{Cu}^+/\text{Cu}^{2+}$ .

This increased arrival energy of the Cu-ions on the substrate allows the alignment of the Cu-ions on the polyester irregular (rugous) surface enabling a uniform coverage of the 3-D polyester [32]. The polyester 3-D presents that rugosity could not be quantified by atomic force microscopy (AFM) since it is beyond the AFM experimental range of  $10 \mu\text{m}$ .

#### 4. Conclusions

This study presents the first evidence for the surface functionalization of polyester by very thin HIPIMS layers of  $\text{TiO}_2/\text{Cu}$  able to inactivate bacteria in the minute range on 3-D surfaces like polyester fabrics. The  $\text{TiO}_2/\text{Cu}$  thin films were uniform, presented adhesive properties and led to repetitive loss of bacteria viability. A faster inactivation kinetics was observed by the  $\text{TiO}_2/\text{Cu}$  films compared to Cu or  $\text{TiO}_2$  sputtered separately.

A polyester sample HIPIMS sputtered for 10 min at 5 A led to a complete inactivation within 10 min under solar simulated light irradiation.

A considerable saving in metal and deposition time (energy) was found with HIPIMS compared to conventional DC/DCP-sputtering on 3-D surfaces. Increasing demand for Cu decreases rapidly the known world reserves. This is important since Cu is a strategically important metal. HIPIMS films of  $\text{TiO}_2/\text{Cu}$  and Cu on polyester have been shown in this study to preclude biofilm formation in the dark and more significantly under light irradiation.

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